

IN THE SPECIFICATION

Please rewrite the paragraph beginning on page 11, line 22, and ending on page 12, line 6, as follows:

a¹ As shown Fig. 8 illustrates a circuit board of a fourth embodiment, the circuit board 81 has a triple layered interconnect structure, that is, includes a top interconnect layer (not shown) on the top surface of the base member 12 having the same configuration as that of the first embodiment, and a first bottom interconnect layer 82 and a second bottom interconnect layer 83 on the bottom surface of the base member 12. The circuit board 81 further includes a floating conductive layer 84, a first dielectric layer 85 and a second dielectric layer 88.

Please rewrite the paragraph on page 12, lines 9-13, as follows:

a² The second bottom interconnect layer 83 is disposed overlying the first bottom interconnect layer 82 and the first dielectric layer 85 and sandwiching the second dielectric layer 88, or disposed between the base member 12 and the second dielectric layer 88.

Please rewrite the paragraph beginning on page 12, line 25, and ending on page 13, line 3, as follows:

a³ The first dielectric layer 85 partially covers the first bottom interconnect layer 82 and sandwiches, with the floating conductive layer 84 and the second bottom interconnect layer 83, the second dielectric layer 88.

Please rewrite the paragraph on page 13, lines 10-17, as follows: